

**Marked-Up Version Showing Claims Changes Made**

Please cancel claim 18 without prejudice or disclaimer as to the subject matter contained therein.

Please amend claim 1 as follows:

1. (Amended) A semiconductor structure, comprising:
  - a first substrate;
  - a second substrate joined to the first substrate;
  - a plurality of contacts between the first substrate and the second substrate; [and]
  - a plurality of first solder bumps connected between the first substrate and the second substrate [for aligning] which align the contacts; and
  - a ledge on at least one of the first substrate and the second substrate, wherein the first solder bumps are arranged in contact with the ledge, such that an upper surface of the contacts and an upper surface of the first solder bumps are co-planar.